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Toelle et al.

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(54) **HEADPHONE ASSEMBLY**

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(51) **LOC (10) Cl.** **14-01**

(52) **U.S. Cl.**

USPC **D14/205**

(58) **Field of Classification Search**

CPC G02B 27/01; H04M 1/05

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379/430, 431; 381/376, 380, 381, 382;

345/8, 7; 455/90.3, 575.1; D16/300;

359/630

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a headphone assembly, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of a headphone assembly according our design;

FIG. 2 is a front elevation view thereof;

FIG. 3 is a back elevation view thereof;

FIG. 4 is a right side elevation view thereof;

FIG. 5 is a left side elevation view thereof;

FIG. 6 is a top elevation view thereof;

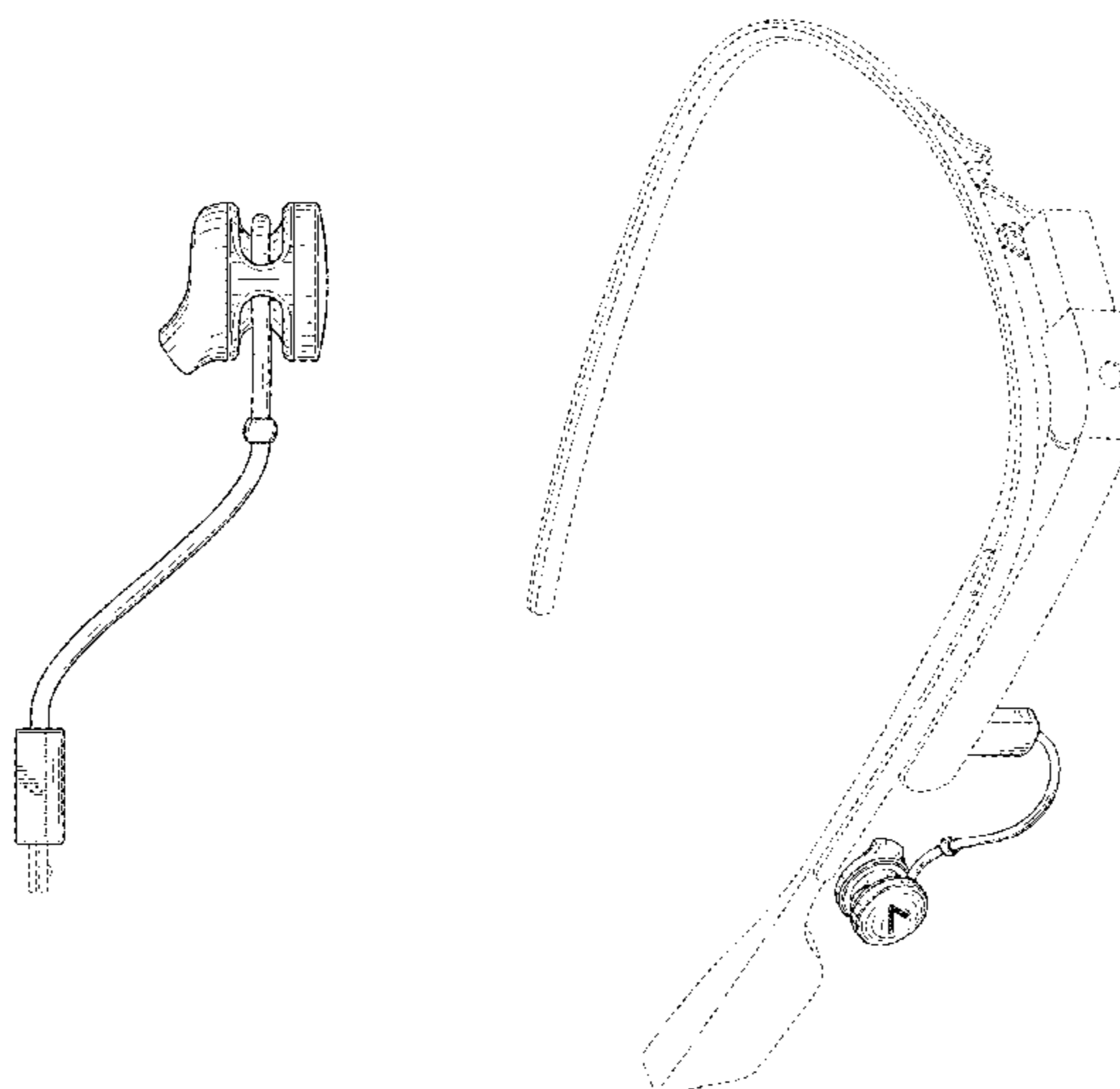
FIG. 7 is a bottom elevation view thereof;

FIG. 8 is a rear perspective view thereof; and,

FIG. 9 is a front perspective view of the headphone assembly of FIG. 1 in a configuration where the headphone assembly is attached with additional environmental features, as shown in the figure.

Broken lines are environmental only and form no part of the claimed design.

1 Claim, 6 Drawing Sheets



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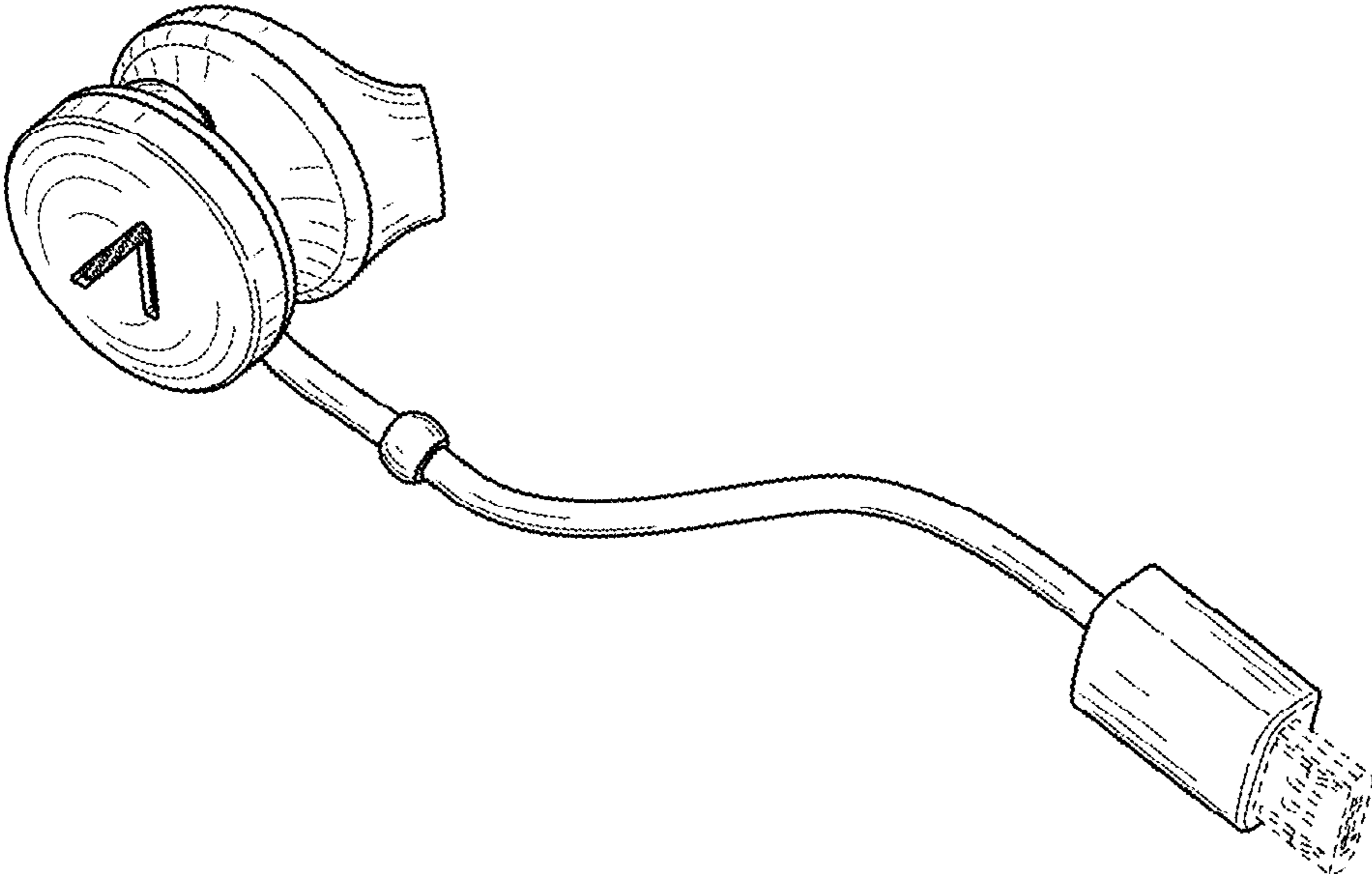


FIG. 1

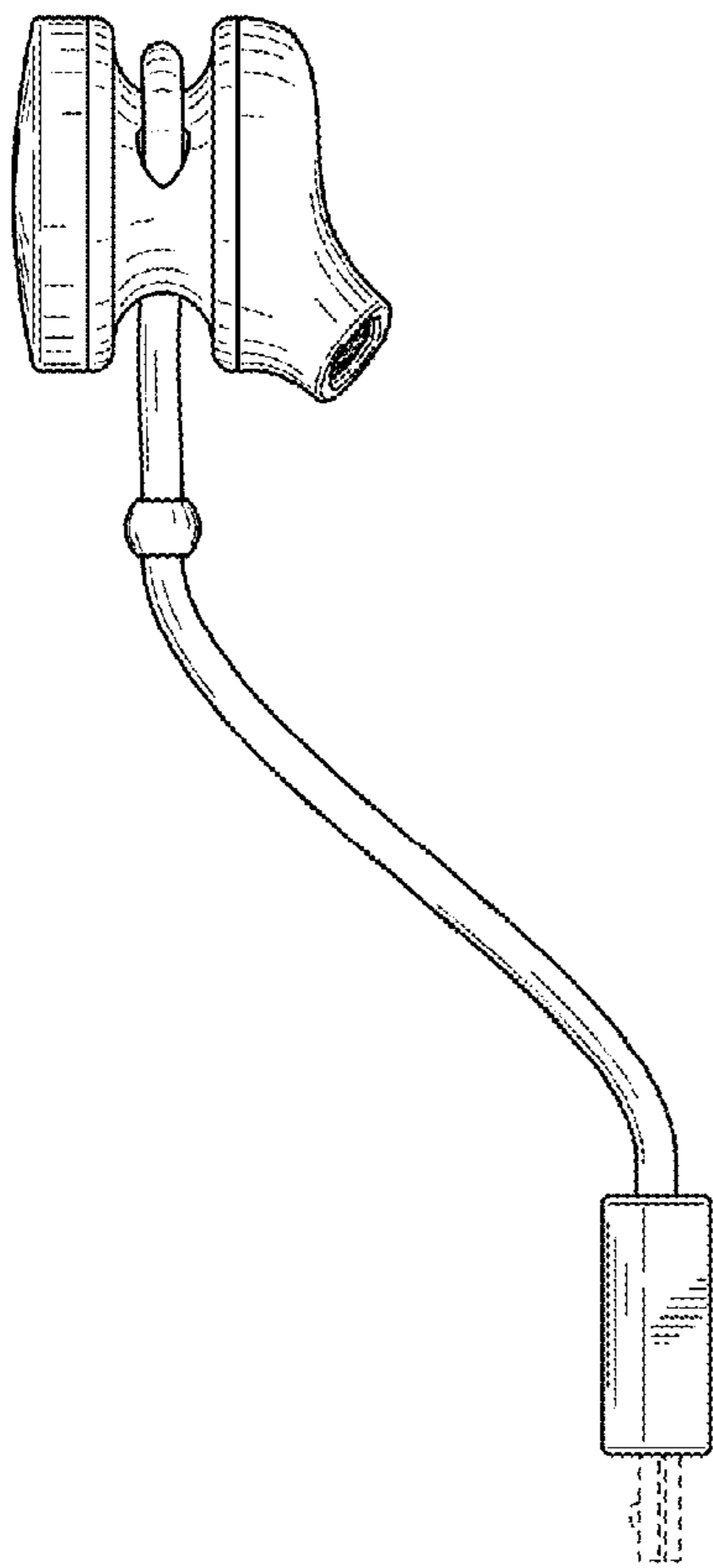


FIG. 2

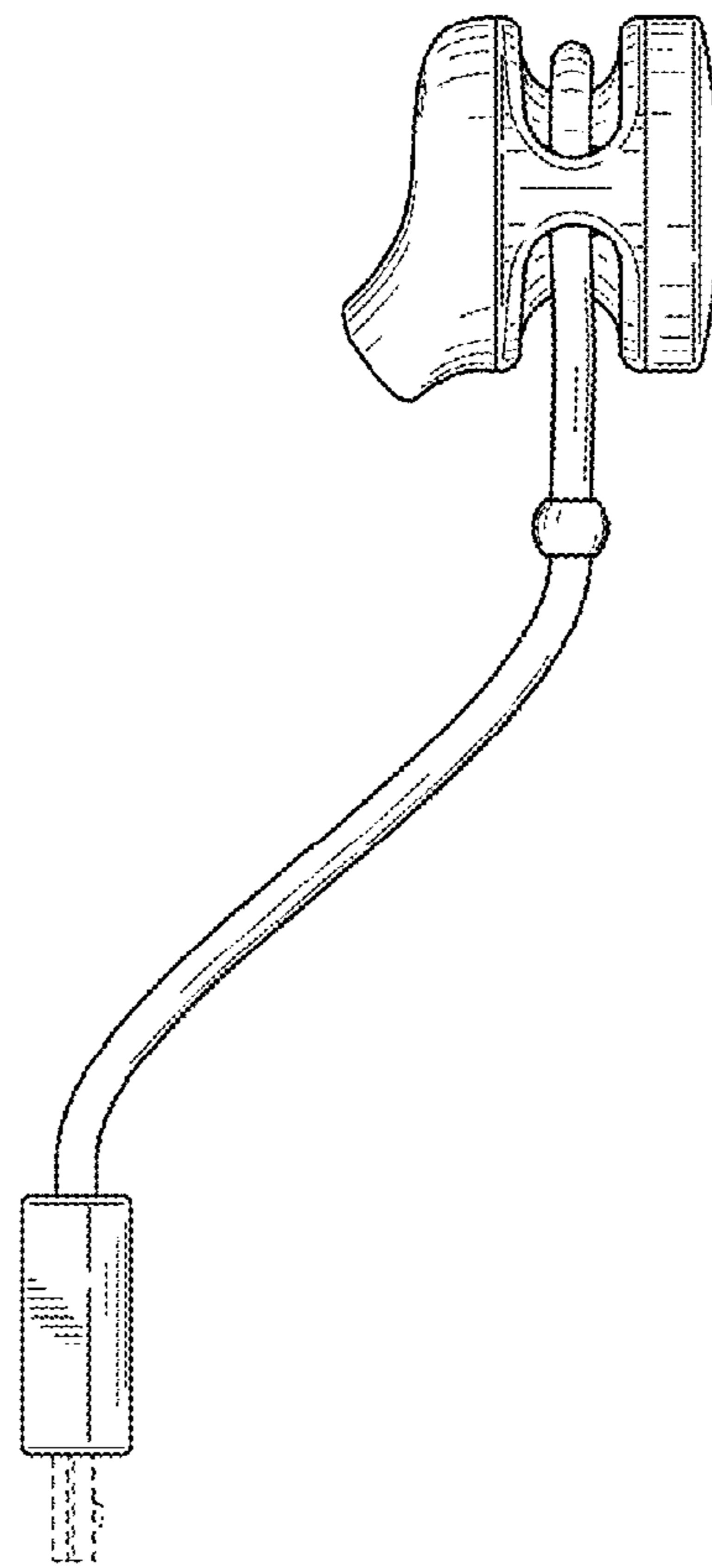


FIG. 3

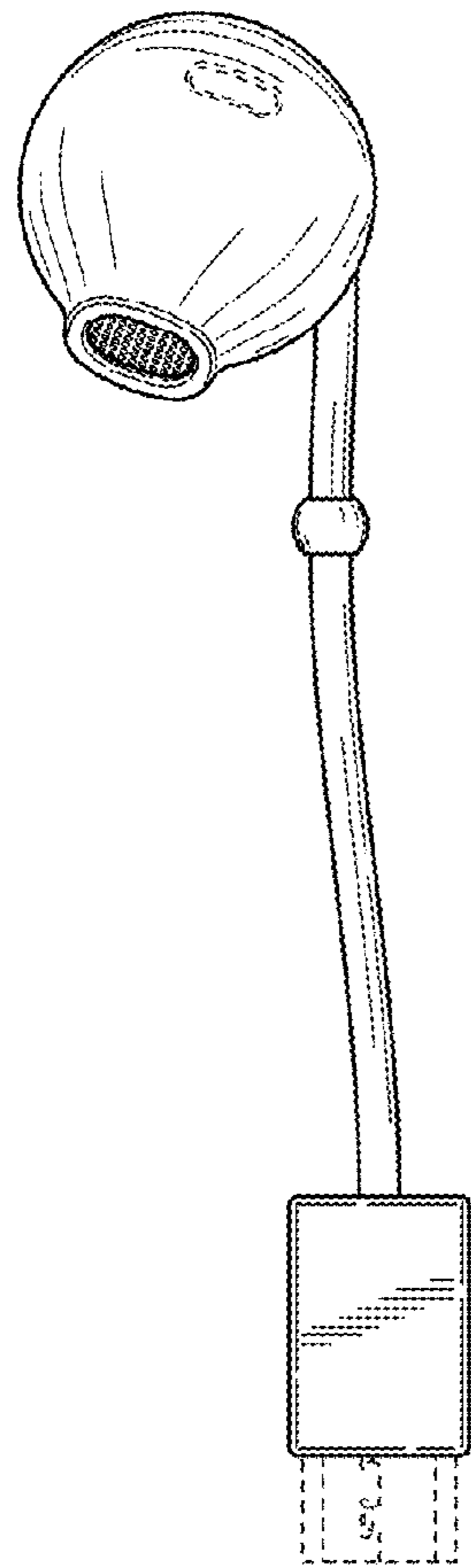


FIG. 4

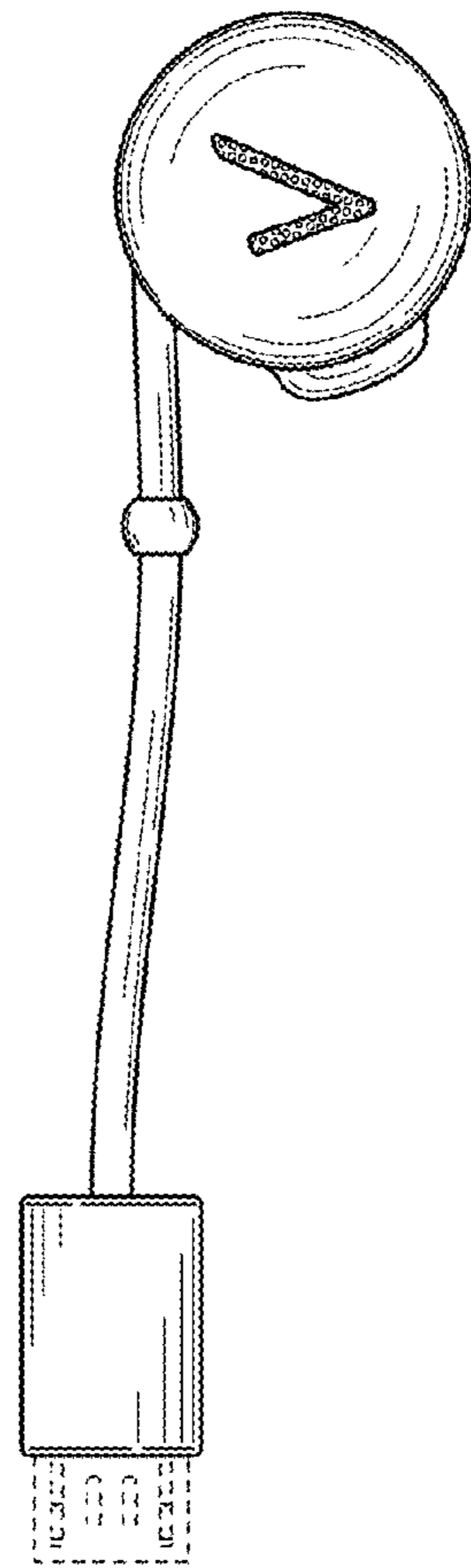


FIG. 5

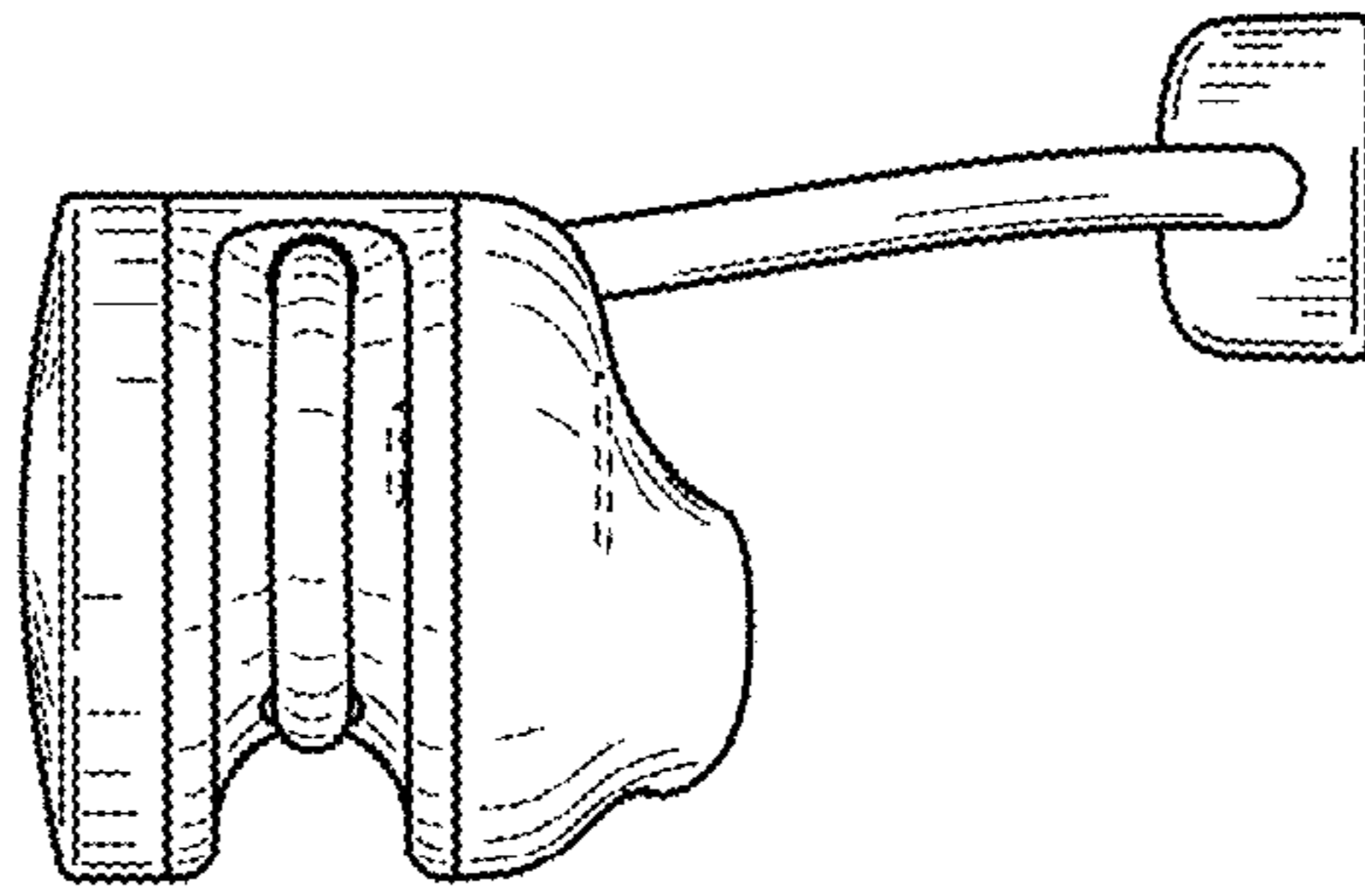


FIG. 6

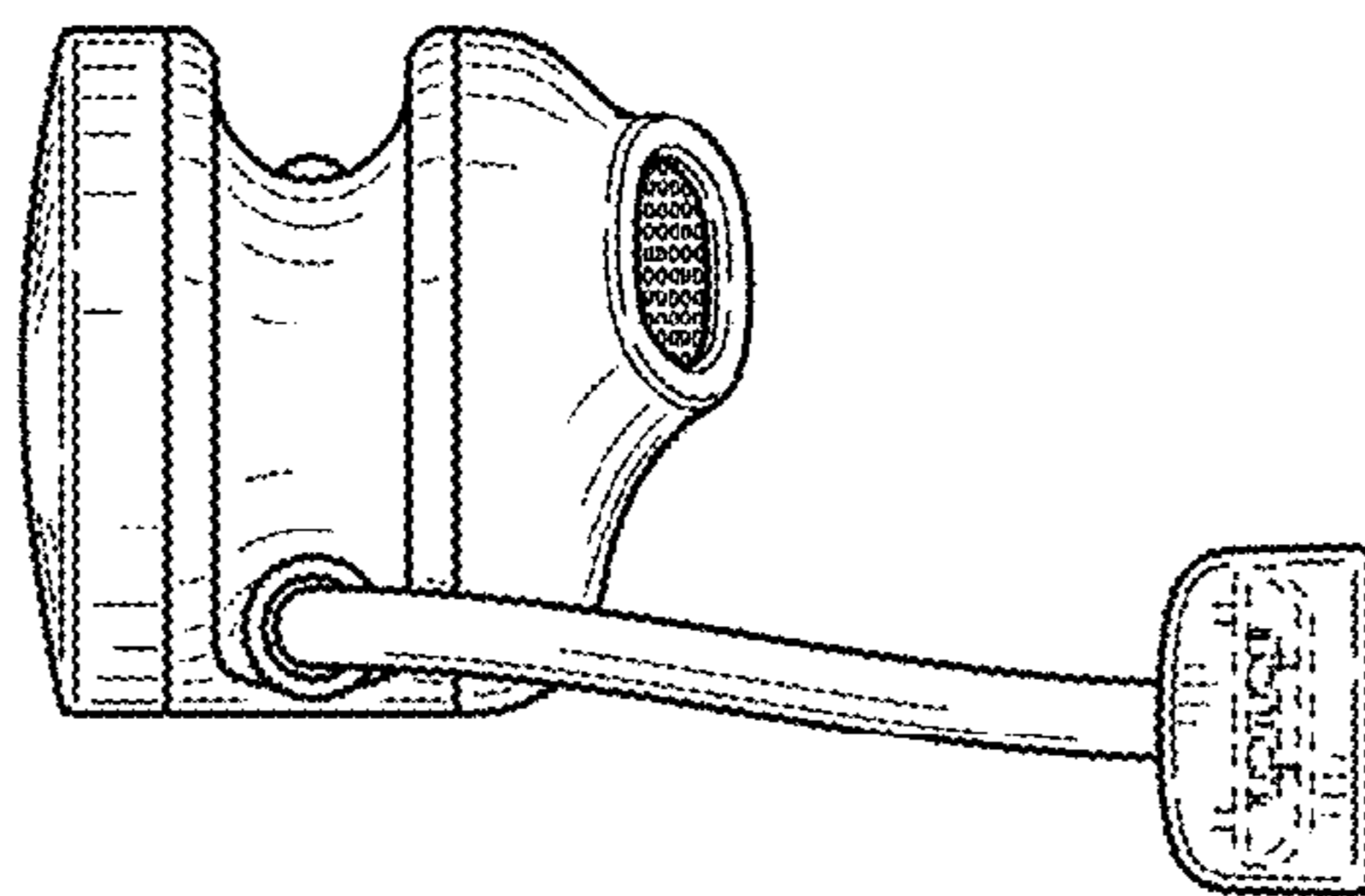


FIG. 7

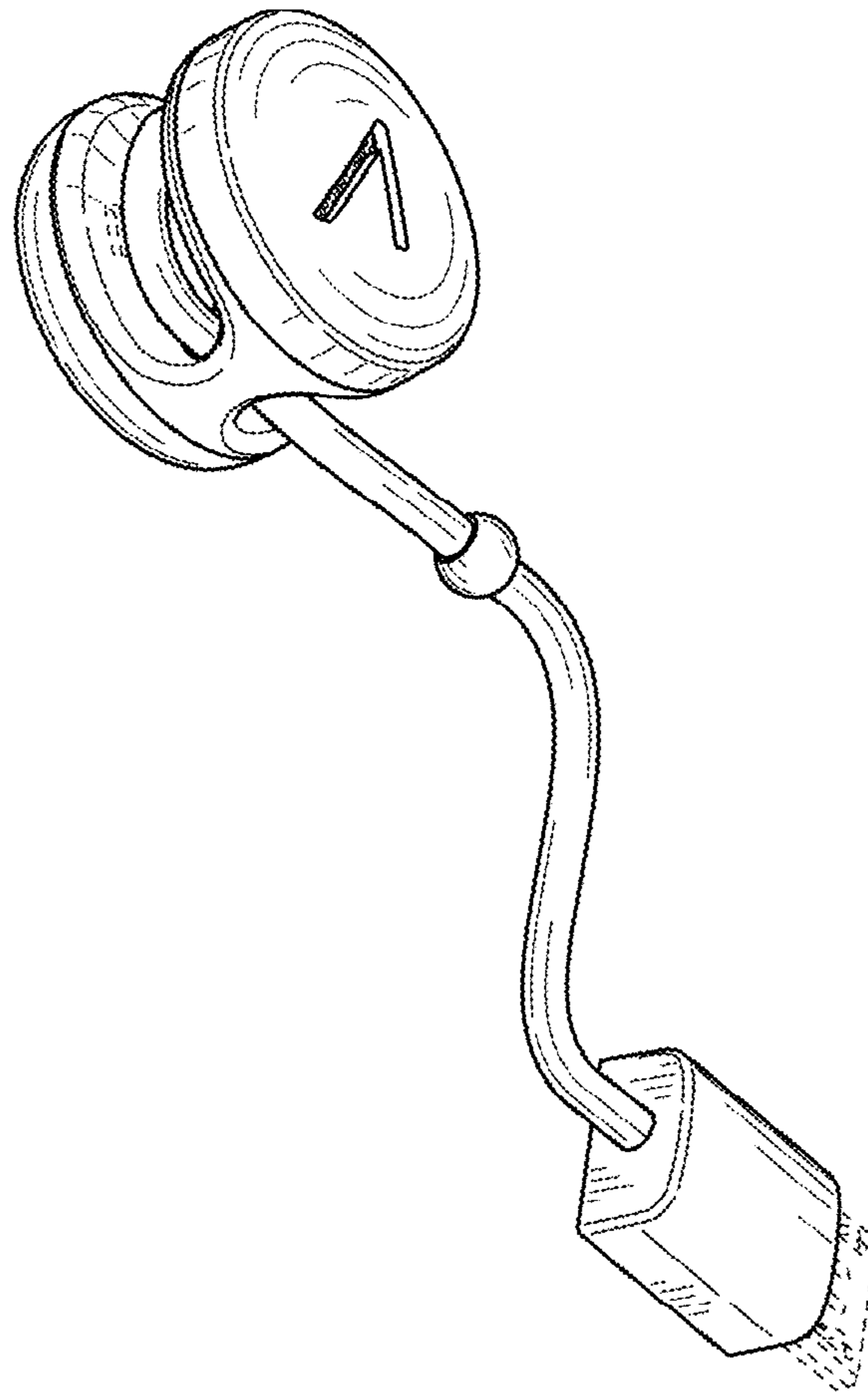


FIG. 8

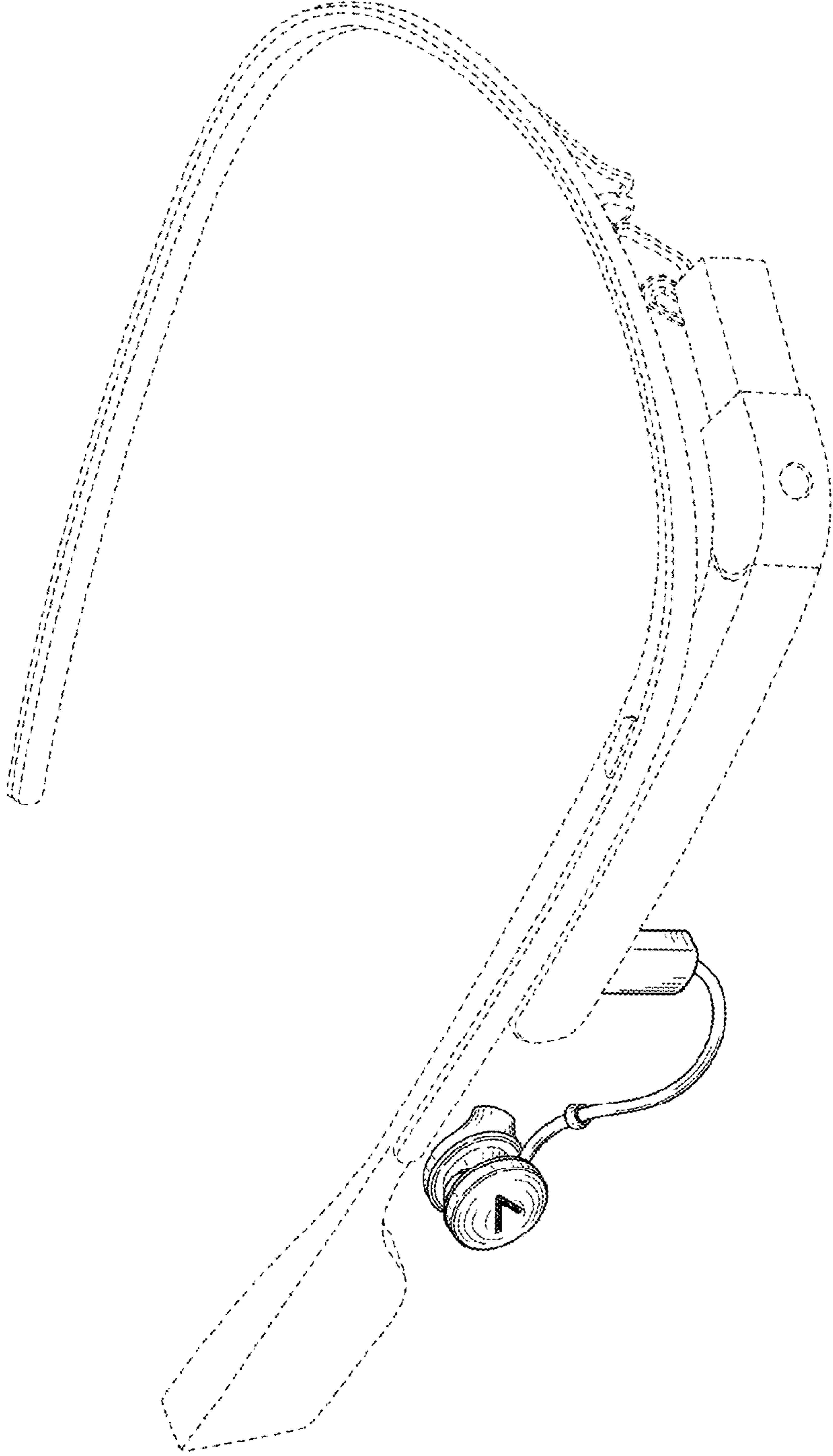


FIG. 9